



# MATERIAL DECLARATION SHEET

Material Number	SMLJ Series			
Product Line	ESD Protection Products			
Compliance Date	1 Jan 2005			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon with metal	0.0105	Silicon	7440-21-3	98	4.9	5
				Nickel	7440-02-0	1.1	0.055	
2	High-melting point Solder paste	Tin-Lead solder	0.0042	Lead	7439-92-1	93.5	1.87	2
				Tin	7440-31-5	5	0.1	
				Silver	7440-22-4	1.5	0.03	
3	Lead frame & clip	Copper alloy	0.0882	Copper	7440-50-8	98.8	41.05	42
				Iron	7439-89-6	0.0213	0.8946	
4	Mould compound	Epoxy material	0.1050	Silica(SiO2)	7631-86-9	70	35	50
				Epoxy resin	68928-70-1	20	10	
				Antimony Trioxide	1309-64-4	5	2.5	
				Phenolic resin	29690-82-2	5	2.5	
5	Plating	Tin solder	0.0021	Tin	7440-31-5	100	1	1
		Total weight	0.2100					

**This Document was updated on:** 26 January 2010

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 7a – high temperature solder